

ABSTRACT

The invention provides a wafer-level package for a micromirror array. The wafer-level package includes a substrate including a wafer having a substrate surface with a plurality of actuatable micromirrors coupled to the substrate surface. An optical window is attached to the substrate surface to form at least one sealed cavity between an inner surface of the optical window and the substrate surface. A beam of light transmitted through the optical window is redirected by at least one actuatable micromirror within the sealed cavity.